1W 730nm High Power IR LED Technical Data Sheet

Part No.: DL-HP10VIRA-1W



Spec No: DL-HP10VIRA-1W Rev No: V.3 Date: May/20/2009 Page: 1 OF 8

Features:

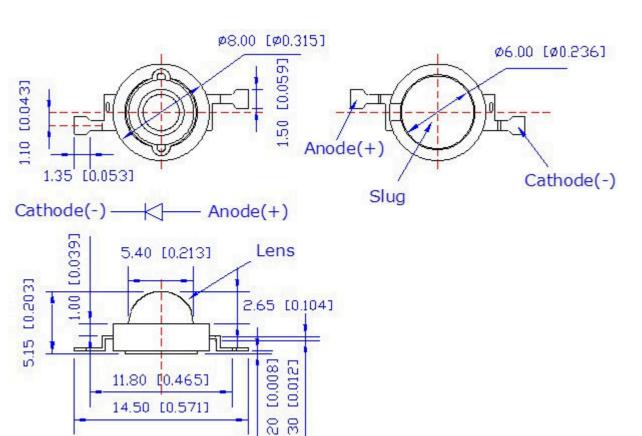
- 1. Very long operating life (up to 100k hours).
- 2. Available in white, green, blue, red, yellow.
- 3. More energy efficient than incandescent and most halogen lamps.
- 4. Low voltage DC operated.
- 5. Cool beam, safe to the touch.
- 6. Instant light (less than 100 ns).
- 7. The product itself will remain within RoHS compliant Version.

Applications:

- 1. Reading lights (car, bus, aircraft).
- 2. Portable (flashlight, bicycle).
- 3. Mini_accent/Uplighters/Downlighters/Orientation.
- 4. Bollards/Security/Garden.
- 5. Cove/Undershelf/Task.
- 6. Automotive rear combination lamps.
- 7. Traffic signaling/Beacons/ Rail crossing and Wayside.
- 8. Indoor/Outdoor Commercial and Residential Architectural.
- 9. Edge_lit signs (Exit, point of sale).
- 10. LCD Backlights/Light Guides.

Spec No: DL-HP10VIRA-1W Rev No: V.3 Date: May/20/2009 Page: 2 OF 8

♦ Mechanical Dimensions:



Part No.	Chip Material	Source Color
DL-HP10VIRA-1W	GaAlAs	730NM

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ± 0.25 mm (.010") unless otherwise noted.

Spec No: DL-HP10VIRA-1W Rev No: V.3 Date: May/20/2009 Page: 3 OF 8

♦ Absolute Maximum Ratings at Ta=25 °C

Parameters	Symbol	Rating	Units
Forward Current	I F	500	mA
Peak Pulse Current (tp≤100μs, Duty cycle=0.25)	I pulse	700	mA
Reverse Voltage	V R	5	V
LED Junction Temperature	T j	125	${\mathbb C}$
Operating Temperature Range	T opr	-40 to +80	${\mathbb C}$
Storage Temperature Range	T stg	-40 to +100	$^{\circ}$
Soldering Time at 260°C (Max.)	T sol	5	Seconds

Notes:

- 1. Proper current derating must be observed to maintain junction temperature below the maximum.
- 2. LEDs are not designed to be driven in reserve bias.

Electrical Optical Characteristics at Ta=25°C

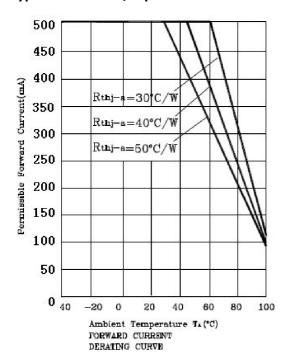
Parameters	Symbol	Min.	Тур.	Max.	Unit	Test Condition	
Viewing Angle [1]	2ϑ _{1/2}		120		Deg	IF=350mA	
Forward Voltage [2]	V _F	1.6		2.2	V	IF=350mA	
Reverse Current	I _R			10	μΑ	V _R =5V	
Peak Emission Wavelength	λ p		730		nm	IF=350mA	
Dominant Wavelength	λ d		730		nm	IF =350mA	
Spectrum Radiation Bandwidth	Δλ		10		nm	IF=350mA	
Power Intensity	Pv	160		240	mw	IF=350mA	

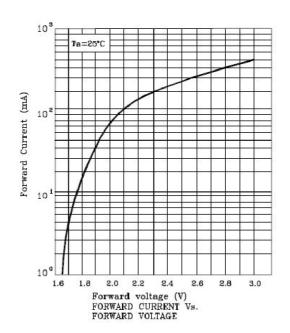
Notes:

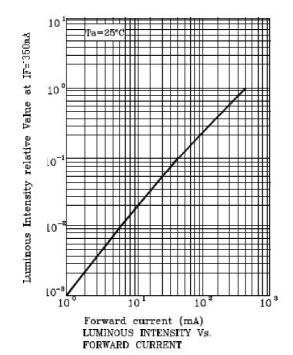
- 1. $2\vartheta 1/2$ is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.
- 2. Forward Voltage measurement tolerance: ±0.1V

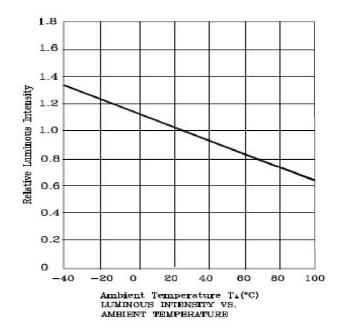
Spec No: DL-HP10VIRA-1W Rev No: V.3 Date: May/20/2009 Page: 4 OF 8

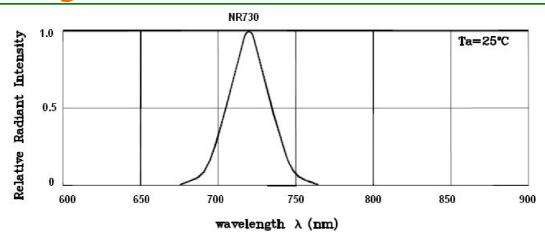
Typical Electrical / Optical Characteristics Curves



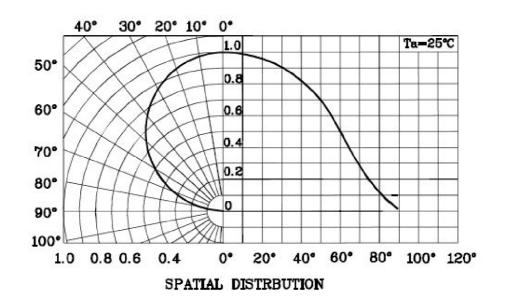








RELATIVE INTENSITY Vs. WAVELENGTH



Spec No: DL-HP10VIRA-1W Rev No: V.3 Date: May/20/2009 Page: 6 OF 8

Reliability Test Items And Conditions:

The reliability of products shall be satisfied with items listed below:

Confidence level: 90%.

LTPD: 10%.

1) Test Items and Results:

No.	Test classification	Test Item	Test conditions	Test Hour/Cycle	Sample Size	Ac/Re
1	Life test	Room temperature DC operating life test	Ta=25±5℃ IF=350mA	1000hrs	60pcs	0/1
2	Environment test	Thermal Shock Test	-10±5°C ←→ +100±5°C 5min 10sec 5min	50cysles	60pcs	0/1
		Temperature Cycle Test	-10±5°C ← → +100±5°C 30min 5sec 30min	50cysles	60pcs	0/1
		High Temperature & High humidity test	Ta=85±5℃ RH=85%±0.5%RH	1000hrs	60pcs	0/1
		High temperature storage	Ta=100±5℃	1000hrs	60pcs	0/1
		Low Temperature Storage	Ta=55±5℃	1000hrs	60pcs	0/1
3	Mechanical test	Resistance to soldering heat	Ta=230±5℃	5sec	60pcs	0/1
		Lead integrity	Load 2.5N (0.25KG) 0°C ~90°C ~0°C	3times	60pcs	0/1

2) Criteria for Judging the Damage:

ltem	Symbol	Test Conditions	Criteria for Judgment		
	ŕ		Min	Max	
Forward Voltage	VF	IF = 350mA		F.V.*)×1.1	
Reverse Current	IR	VR=5V		F.V.*)×2.0	
Luminous Intensity	IV	IF = 350mA	F.V.*)×0.7		

*) F.V.: First Value.

Spec No: DL-HP10VIRA-1W Rev No: V.3 Date: May/20/2009 Page: 7 OF 8

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www.ledlight-components.com

Precautions For Use:

1. Over-current-proof

Though HP10 has conducted ESD protection mechanism, customer must not use the device in reverse and should apply resistors for extra protection. Otherwise slight voltage shift may cause enormou current change and burn out failure would happen.

- Storage
 - 1) Do not open moisture proof bag before the products are ready to use.
 - 2) Before opening the package, the LEDs should be kept at 30° C or less and 90%RH or less.
 - 3) The LEDs should be used within a year.
 - 4) After opening the package, the LEDs should be kept at 30° C or less and 70%RH or less.
 - 5) The LEDs should be used within 168 hours (7 days) after opening the package.
 - 6) If the moisture absorbent material (silicone gel) has faded away or the LEDs have exceeded the storag time, baking treatment should be performed using the following conditions.
 - 7) Pre-curing treatment: $60\pm5^{\circ}$ °C for 24 hours.
- 3. Thermal Management
 - 1) Because HP10 LED is a high power dissipation device, special and sufficient consideration in thermal management design must be made to optimize the thermal performance.
 - 2) Heat sink design is implemented in the device for an additional thermal connection. Since the device is capable of SMT process, tin must be spread both heat sink and solder pads areas to dissipate the heat.
 - 3) A high thermal conductivity substrate, such as Aluminum or Copper plate etc, must be applied for external thermal management. It is strongly recommended that the outer heat sink or PCB dimension per LED cannot be less than 25 x 25 x 1 (L x W x H) mm. The materials for outer heat sink can be FR4 on Aluminum, MCPCB, or FPC on Aluminum.
 - 4) Special thermal designs are also recommended to take in outer heat sink design, such as FR4 PCB on Aluminum with thermal vias or FPC on Aluminum with thermal conductive adhesive, etc.
 - 5) Sufficient thermal management must be conducted, or the die junction temperature will be over the limit under large electronic driving and LED lifetime will decrease critically.
- 4. Soldering Condition
 - 1) Soldering should not be done more than two times.
 - 2) While soldering, do not put stress on the LEDs during heating.
 - 3) After soldering, do not warp the circuit board.
- 5. Soldering Iron
 - 1) For prototype builds or small series production runs it is possible to place and solder the LED by hand.
 - 2) Dispensing thermal conductive glue or grease on the substrates and follow its curing spec. Press LED housing to closely connect LED and substrate.
 - 3) It is recommended to hand solder the leads with a solder tip temperature of 280°C for less than 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal.
 - 4) Be careful because the damage of the product is often started at the time of the hand solder.

Spec No: DL-HP10VIRA-1W Rev No: V.3 Date: May/20/2009 Page: 8 OF 8